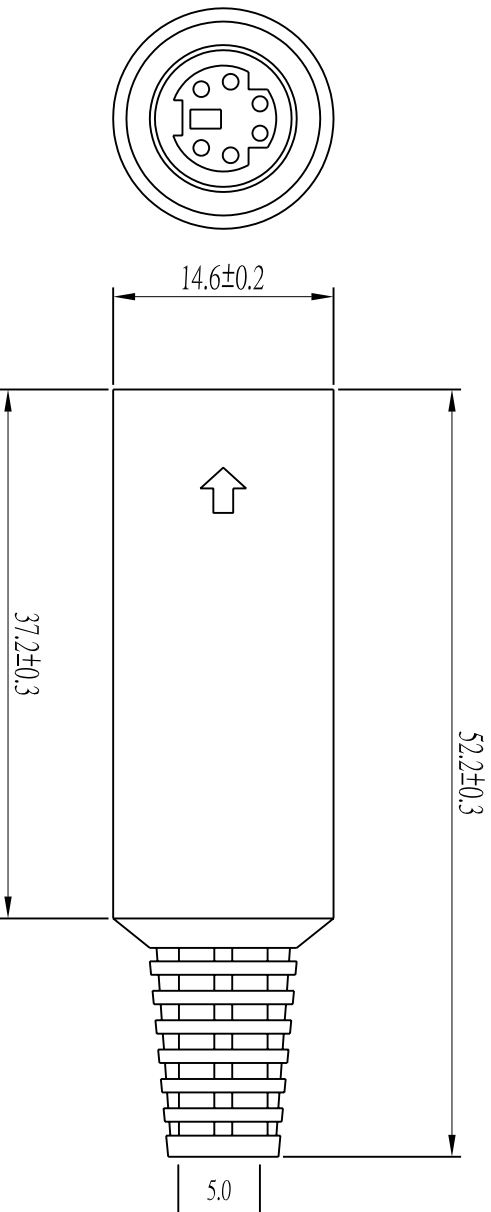


REV.	ECN NO	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Note:

1.Material:

- 1.1 Insulator: High temperature thermoplastic with g.f.U194v-0
- 1.2 Contact: Copper alloy,t=0.20mm
- 1.3 Shell: Spec.t=0.30mm

2.Specification:

- 2.1 Current rating: 1 A Max.
- 2.2 Dielectric withstanding voltage: 750 V(ac) for 1 min.
- 2.3 Contact resistance: 30 mΩ Max.
- 2.4 Insulation resistance: 1000 MΩ Min.
- 2.5 Total mating force: 3.0 Kgf Max.
- 2.6 Total unmating force: 0.5 Kgf Min.
- 2.7 Temperature range: -55°C~85°C

NO.OF CONTACT	3	4	5	6	7	8
PART NO.	MD-3S	MD-4S	MD-5S	MD-6S	MD-7S	MD-8S
POSITION						

8	Back-shell			
7	Front-shell			
6	Chip			No finish
5	Contact			Selective Au plated on mating area
4	Contact			
3	Contact			
2	Contact			
1	Housing			Black
No.	Name	Qty	Part No.	Finish

PART NO:		MATERIAL:		PART NAME:	
MODEL NO:		FINISH:		HSI-CHIN ELECTRONICS CO.,LTD	
UNIT: mm	SIZE:	COLOR:		MINI DIN FEMALE ASSEMBLE	
TOLERANCE UNSPECIFIED		DR: <i>YuWong</i>		DWG NO: HC-021-06	
.x ±0.3	.xx ±0.20	CHK: <i>Mick</i>		SCALE: 2:1	
.xxx ±0.100	.1* ±0.100	APP: <i>Keat</i>		SHEET: 1 of 1	
ANG.	F.T			REV: A0	

